Patent Details

Title of the Patent	**:**	Epoxy Resin based Adhesive and Preparation Method Thereof
Patentee	**:**	• Laboratory for Advanced Research in Polymeric Materials (LARPM), Central Institute of Petrochemicals Engineering & Technology (CIPET) • Institute of Plasma Research (IPR)
Name of the Inventors	**:**	**LARPM CIPET** 1. Dr. Bishnu Prasad Panda (CIPET) 2. Dr. Smita Mohanty (CIPET) 3. Dr. Sanjay K. Nayak **IPR :** 1. Dr. Manoj Kumar Gupta (IPR)
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Summary of the Innovation/ Patent/ Technology	**:**	**Invention details:** Thermally conductive epoxy adhesive composition that acts as a TIM in between the heat-generating source and heat sink with higher conduction with a lower filler loading percentage. **Importance of technology** TIM with higher thermal conductivity of approximately 6 W/mK which is higher than the commercially available adhesives and can suitably adhere metal-metal joints **Viability of commercialization:** Thermal Conductivity and other performance characteristics are better than the commercially available adhesives **Benefit to society** Environmental issues pertaining to welding of metal to metal can be avoided/resolved using the adhesive.
Graphical Abstract/ Image of the Product	**:**	